MATERIAL DECLARATION SHEET

Material Number	ESD Suppressing Device CDDFN10-0524P			
Product Line	Semiconductor Products			
Compliance Date	2013/8/2			
RoHS Compliant	Yes	MSL	3	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Wafer	Silicon	0.00035	Silicon	7440-21-3	100.00%	7.99%	7.99%
2	Lead Frame	Copper alloy	0.00180	Copper	7440-50-8	95.445%	41.19%	43.15%
			0.00005	Iron	7439-89-6	2.40%	1.04%	
			0.000002	Phosphorus	7723-14-0	0.10%	0.04%	
			0.000003	Zinc	7440-66-6	0.15%	0.06%	
			0.0000001	Lead	7439-92-1	0.005%	0.00%	
			0.00004	Silver	7440-22-4	1.90%	0.82%	
3	Epoxy	Polymer	0.00007	Acrylic Copolymer	Trade Secret	60.00%	1.51%	2.51%
			0.00002	Epoxy Resin	Trade Secret	15.00%	0.38%	
			0.00001	Hardener	Trade Secret	12.50%	0.31%	
			0.00001	Amorphous Silica	68583-49-3	12.50%	0.31%	
4	Wire	Noble metal	0.000069	Gold	7440-57-5	99.99%	1.57%	1.60%

			0.000000007	Misc., not to declare	N/A	0.01%	0.03%	
5	Mold Compound	Polymer	0.000092	Epoxy Resin	Trade Secret	5.00%	2.10%	42.0073%
			0.000092	Phenol Resin	Trade Secret	5.00%	2.10%	
			0.001362	Silica(Amorphous) A	60676-86-0	74.00%	31.09%	
			0.000276	Silica(Amorphous) B	7631-86-9	15.00%	6.30%	
			0.000018	Carbon Black	1333-86-4	1.00%	0.42%	
6	Plating	plating	0.000120	Tin	7440-31-5	99.9%	2.74%	2.7427%
			0.0000001	Misc., not to declare	N/A	0.1%	0.0027%	
		Total weight	0.0043799 g					

This Document was updated on: 2013/8/2

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.

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